

N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☒ Trench Power SGT technology
- ☒ Low Gate Charge
- ☒ Very low on-resistance $R_{DS(ON)}$

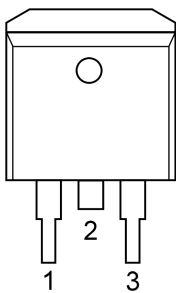
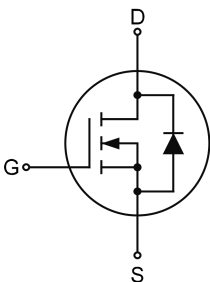
1.2 Applications

- ☒ Power Tool appliances
- ☒ High power inverter system
- ☒ BMS appliances

1.3 Quick reference

- ☒ $BV \geq 45\text{ V}$
- ☒ $P_D \leq 329\text{ W}$
- ☒ $I_D \leq 350\text{ A}$
- ☒ $R_{DS(ON)} \leq 1.8\text{ m}\Omega @V_{GS} = 10\text{ V}$

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate(G)	 Top View TO-263	
2	Drain(D)		
3	Source(S)		

3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_A=25^{\circ}\text{C}$	45	-	V
V_{GS}	Gate-Source Voltage	$T_A=25^{\circ}\text{C}$	-	± 20	V
I_D	Continuous Drain Current	$T_C=25^{\circ}\text{C}, V_{GS}=10\text{ V}$	-	350	A
		$T_C=100^{\circ}\text{C}, V_{GS}=10\text{ V}$	-	221	A
I_{DM}	Pulsed Drain Current	$T_A=25^{\circ}\text{C}, V_{GS}=10\text{ V}$	-	1400	A
I_{AS}	Avalanche Current		-	65	A
E_{AS}	Single Pulsed Avalanche Energy	$L=0.3\text{ mH}$	-	634	mJ
P_D	Drain Power Dissipation -Derating Factor	$T_C=25^{\circ}\text{C}$	-	147	W
			-	2	W/ $^{\circ}\text{C}$
T_J, T_{stg}	Operating Junction and Storage Temperature Range		-55	150	$^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient, Steady-State		-	50	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case, Steady-State		-	0.38	

Notes:

- * Single pulse width limited by maximum junction temperature.
- ** $T_J=25^{\circ}\text{C}, V_{DD}=32\text{ V}, V_{GS}=10\text{ V}, L=0.3\text{ mH}, R_g=2\ \Omega$
- *** P_D is based on $T_J(\text{MAX})=150^{\circ}\text{C}$.

4. Marking Information

Product Name	Marking
KJ018N045D	KJ018N045D XXXXXX-X

5. Ordering Code

Product Name	Package	Reel size	Tape width	Quantity (pcs)
KJ018N045D	TO-263	13"	24 mm	800

Note: KJ018N045D defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C)

6. Electrical Characteristics (T_A=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0 V, I _{DS} =250 μA	45	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250 μA	1.2	-	2.0	V
I _{DSS}	Zero Gate Voltage Source Current	V _{DS} =45 V, V _{GS} =0 V, T _J =25℃	-	-	1	μA
		V _{DS} =45 V, V _{GS} =0 V, T _J =100℃	-	-	100	
I _{GSS}	Gate-Body Leakage Current	V _{DS} =0 V, V _{GS} =±20 V	-	-	±100	nA
R _{DS(ON)}	Drain-Source On-Resistance	V _{GS} =10 V, I _{DS} =50 A	-	1.5	1.8	mΩ
		V _{GS} =4.5 V, I _{DS} =50 A	-	1.8	2.3	mΩ
g _{FS}	Forward Transconductance	V _{DS} =10 V, I _D =10 A	-	60	-	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =20 V, V _{GS} =0 V, Frequency=1 MHz	-	7542	-	pF
C _{oss}	Output Capacitance		-	1176	-	
C _{rss}	Reverse Transfer Capacitance		-	146	-	
Switching Parameters						
Q _g	Total Gate Charge	V _{DS} =20 V, V _{GS} =10 V, I _{DS} =20 A	-	84	-	nC
Q _{gs}	Gate-Source Charge		-	30	-	
Q _{gd}	Gate-Drain Charge		-	17	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} =20 V, V _{GS} =10 V, R _G =1.6 Ω, I _D =20 A	-	12	-	ns
t _r	Turn-on Rise Time		-	48	-	
t _{d(off)}	Turn-off Delay Time		-	24	-	
t _f	Turn-off Fall Time		-	9.2	-	
Diode Characteristics						
V _{SD}	Diode Forward Voltage	I _{SD} =20 A, V _{GS} =0 V	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	V _{GS} =0 V, I _F =20 A, dI _{SD} /dt=100 A/μs	-	24	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	44	-	nC

7. Typical Characteristics

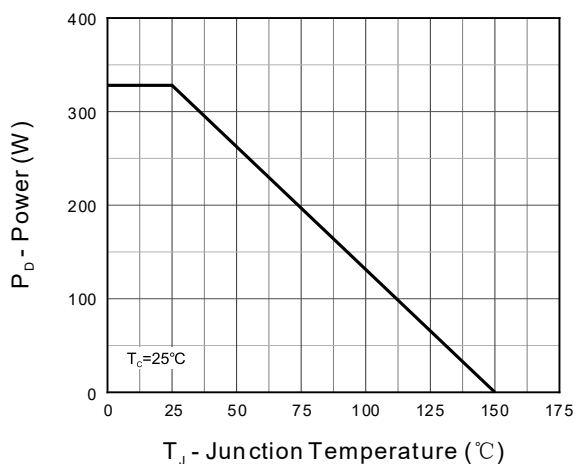


Figure 1. Power Capability

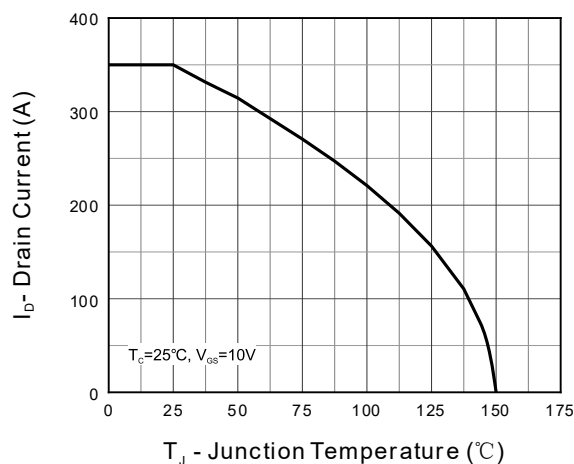


Figure 2. Current Capability

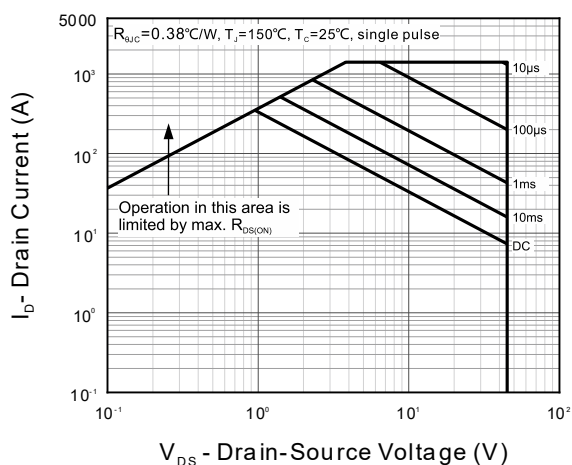


Figure 3. Safe Operation Area

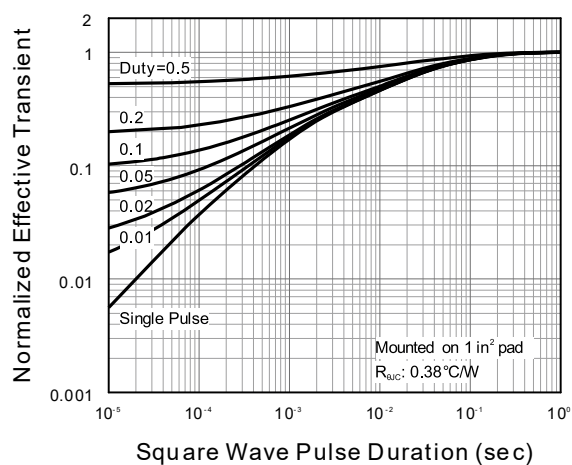


Figure 4. Transient Thermal Impedance

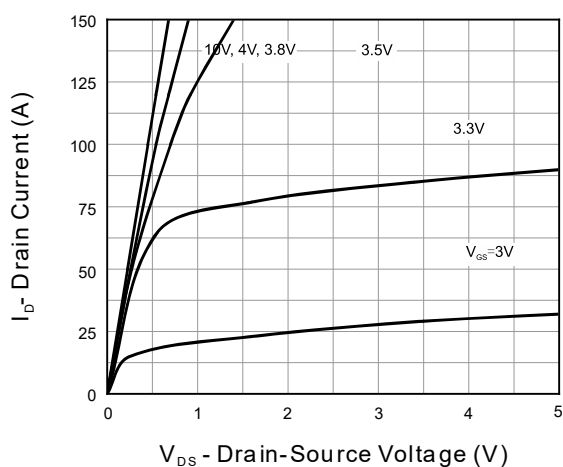


Figure 5. Output Characteristics

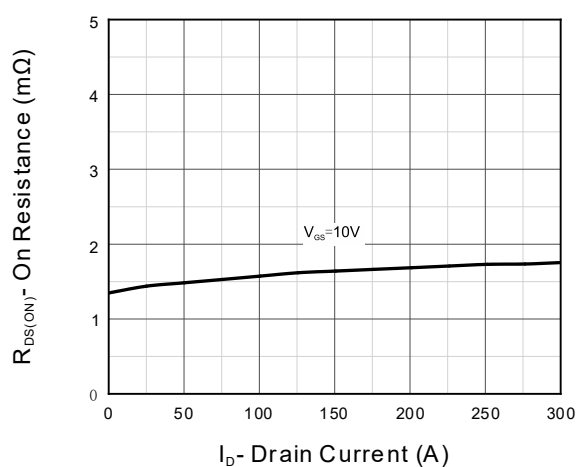


Figure 6. On Resistance

7. Typical Characteristics(cont.)

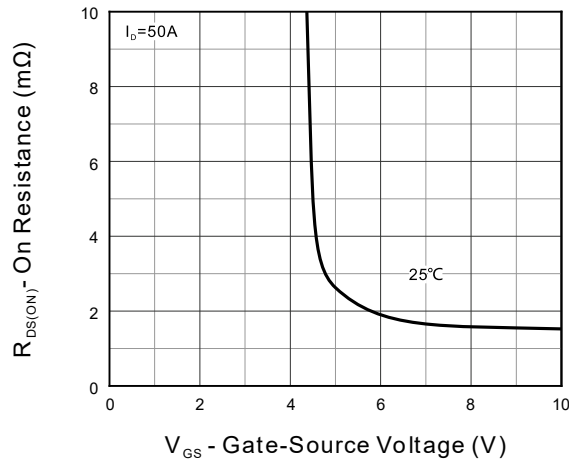


Figure 7. Transfer Characteristics

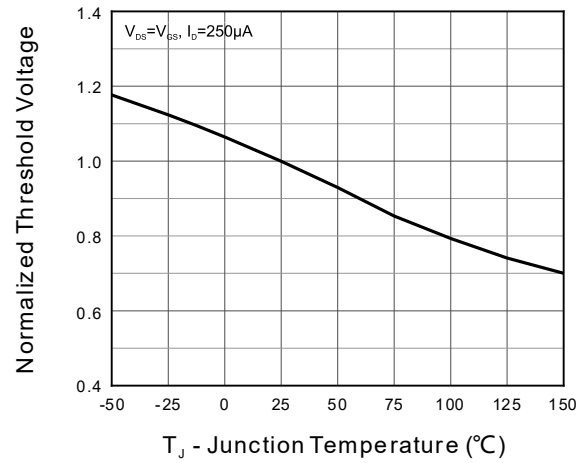


Figure 8. Normalized $V_{GS(th)}$

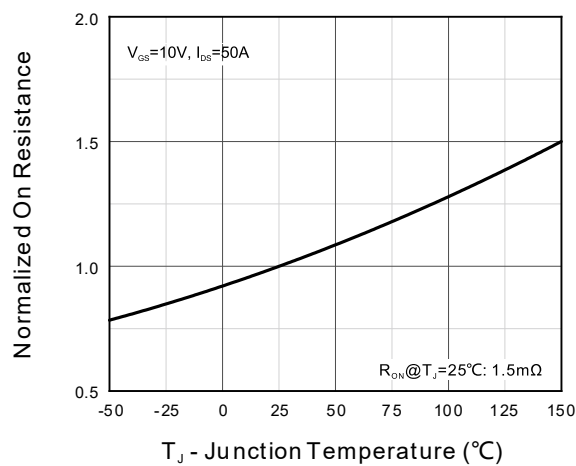


Figure 9. Normalized On Resistance

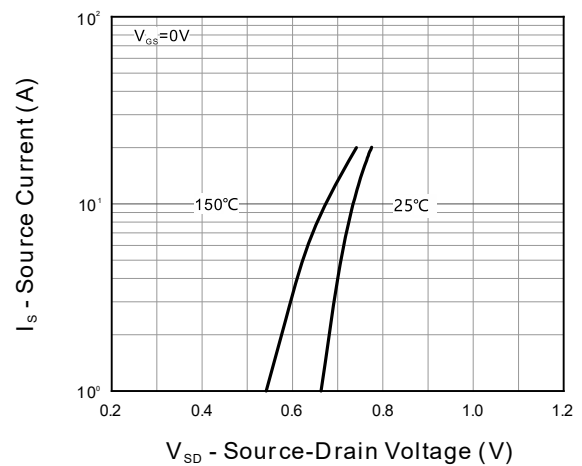


Figure 10. Diode Forward Current

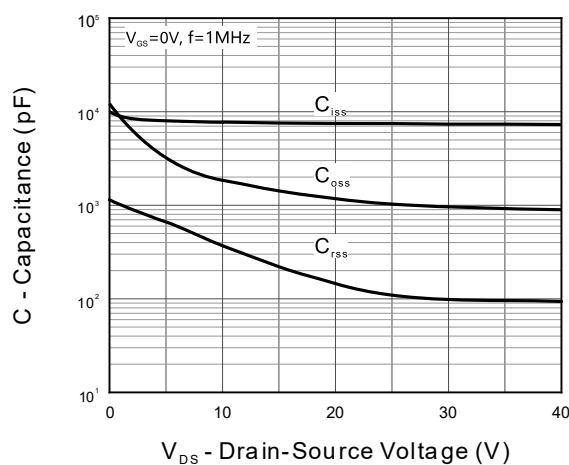


Figure 11. Capacitance

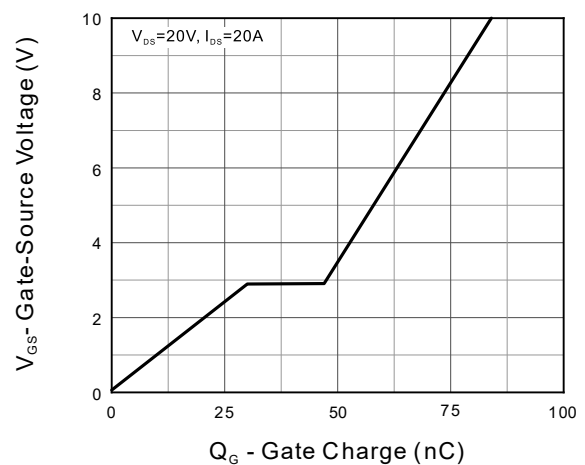
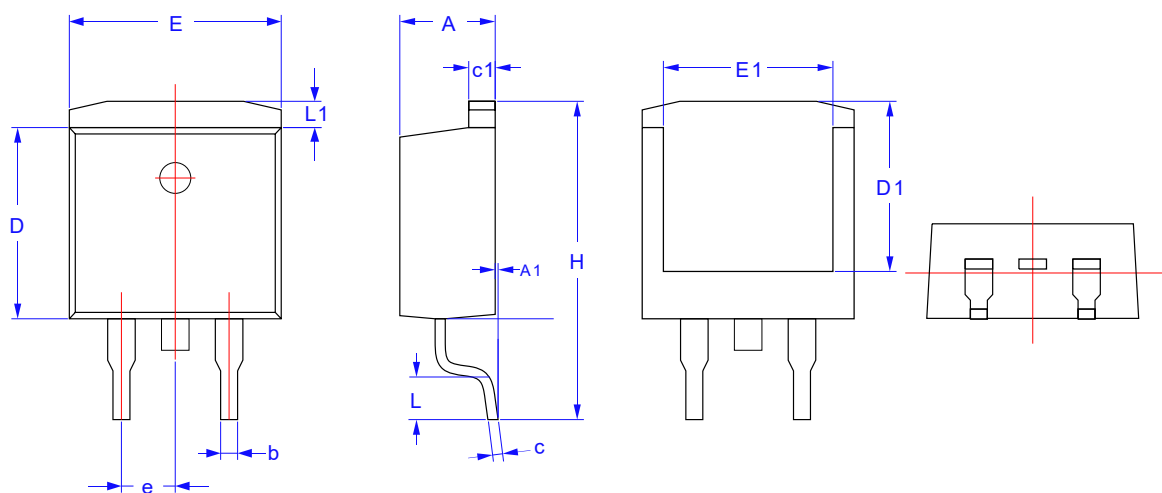


Figure 12. Gate Charge

8. Package Dimensions

TO-263 Package



TOP VIEW

SIDE VIEW

BOTTOM VIEW

SIDE VIEW

Symbol	Dimensions in Millimeters	
	MIN	MAX
A	4.40	4.70
A1	0.00	0.25
b	0.70	0.90
c1	0.40	0.55
c2	1.25	1.35
D	9.00	9.30
D1	7.40	8.40

Symbol	Dimensions in Millimeters	
	MIN	MAX
E	9.80	10.40
E1	7.20	8.40
e	2.54 BSC	
H	14.90	15.25
L	2.00	2.50
L1	1.00	1.40